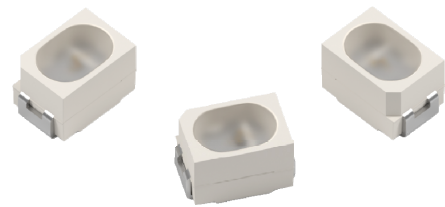


AA2214ZGS-AMT

2.2 x 1.4 mm Surface Mount LED Lamp



DESCRIPTIONS

- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- 2.2 mm x 1.4 mm, 1.3 mm high
- Low power consumption
- Available on tape and reel
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

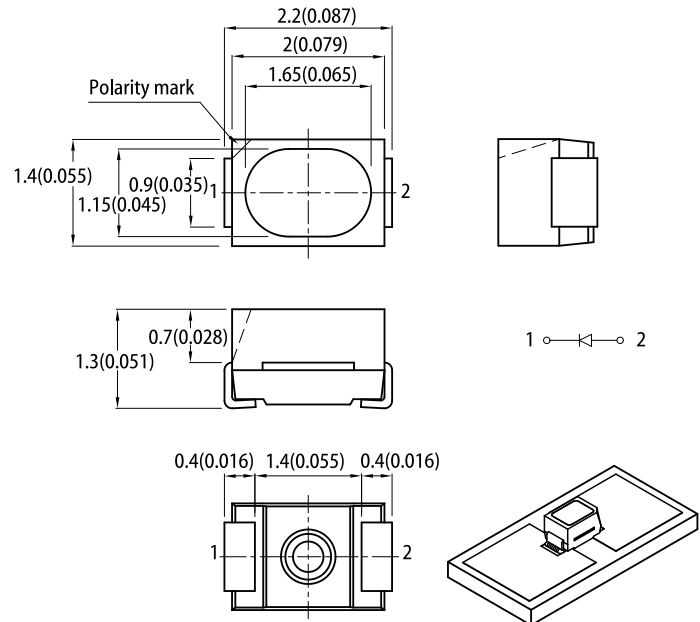
- Traffic signaling
- Backlighting (illuminated advertising , general lighting)
- Interior and exterior automotive lighting
- Substitution of micro incandescent lamps
- Reading lamps
- Signal and symbol luminaire for orientation
- Marker lights (e.g. Steps, exit ways, etc)
- Decorative and entertainment lighting
- Indoor and outdoor commercial and residential architectural lighting

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

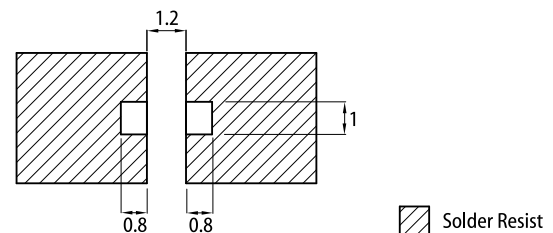


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA ^[2]			Viewing Angle ^[1]
			Code.	Min.	Max.	2θ1/2
AA2214ZGS-AMT	■ Green (InGaN)	Water Clear	R	400	500	120°
			S	500	700	
			T	700	1000	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: $\pm 15\%$.
3. Luminous intensity value is traceable to CIE127-2007 standards.
4. LEDs will be provided from the listed bin codes. The bins delivered to the customer will be at Kingbright's discretion.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value				Unit
			Code.	Min.	Typ.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Green	-	-	515	-	nm
Dominant Wavelength I _F = 20mA	$\lambda_{\text{dom}}^{[1]}$	Green	1	515	-	520	nm
			2	520	-	525	
			3	525	-	530	
			4	530	-	535	
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	$\Delta\lambda$	Green	-	-	30	-	nm
Forward Voltage I _F = 20mA	V _F ^[2]	Green	-	-	3.3	4.1	V
Reverse Current (V _R = 5V)	I _R	Green	-	-	-	50	μA
Temperature Coefficient of λ_{peak} I _F = 20mA, -10°C ≤ T ≤ 100°C	TC _{λ_{peak}}	Green	-	-	0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I _F = 20mA, -10°C ≤ T ≤ 100°C	TC _{λ_{dom}}	Green	-	-	0.03	-	nm/°C
Temperature Coefficient of V _F I _F = 20mA, -10°C ≤ T ≤ 100°C	TC _V	Green	-	-	-2.9	-	mV/°C

Notes:

1. The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.
5. LEDs will be provided from the listed bin codes. The bins delivered to the customer will be at Kingbright's discretion.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

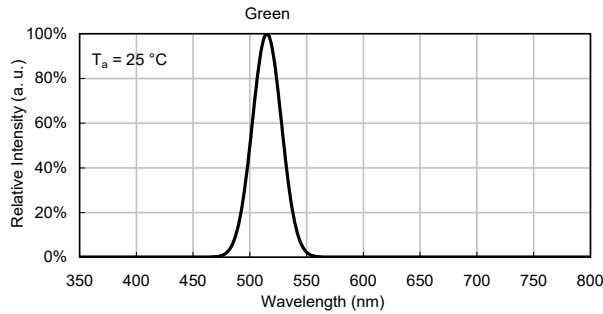
Parameter	Symbol	Value	Unit
Power Dissipation	P _D	82	mW
Reverse Voltage	V _R	5	V
Junction Temperature	T _j	115	°C
Operating Temperature	T _{op}	-40 to +100	°C
Storage Temperature	T _{stg}	-40 to +110	°C
DC Forward Current	I _F	20	mA
Peak Forward Current	I _{FP} ^[1]	100	mA
Electrostatic Discharge Threshold (HBM)	-	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	490	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	350	°C/W

Notes:

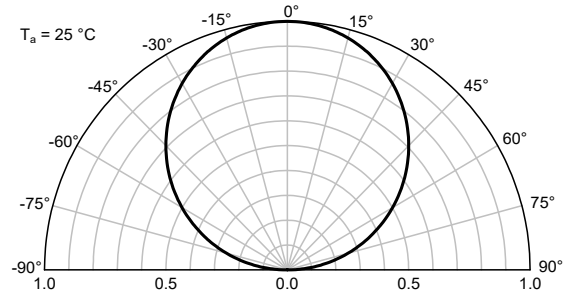
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

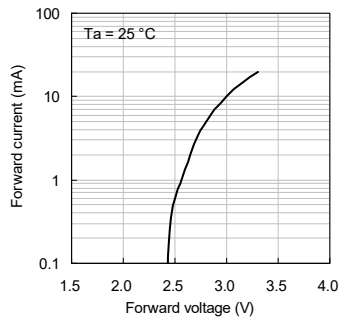


SPATIAL DISTRIBUTION

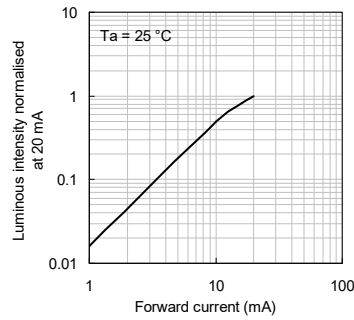


GREEN

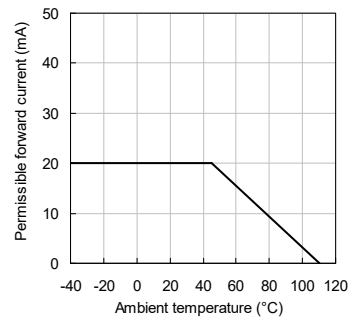
Forward Current vs. Forward Voltage



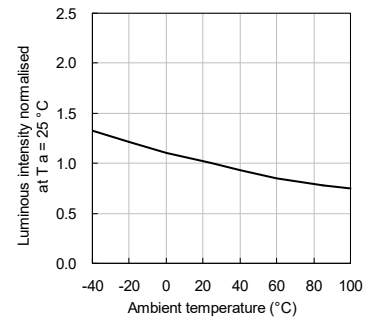
Luminous Intensity vs. Forward Current



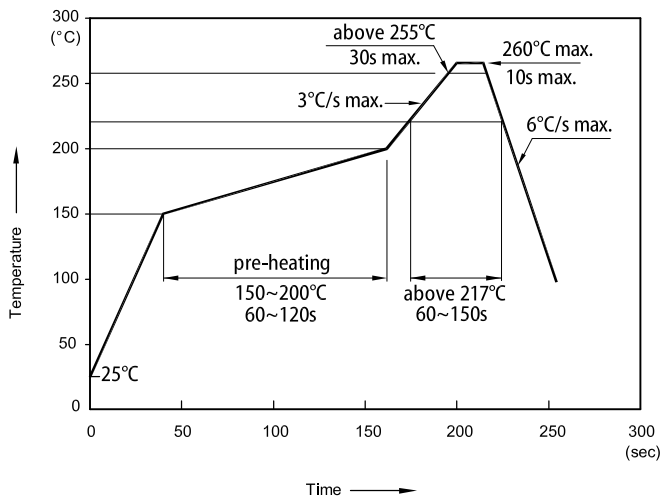
Forward Current Derating Curve



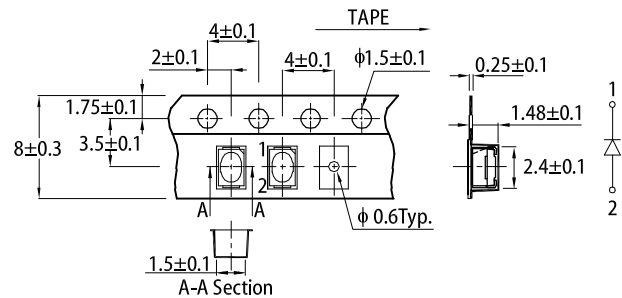
Luminous Intensity vs. Ambient Temperature



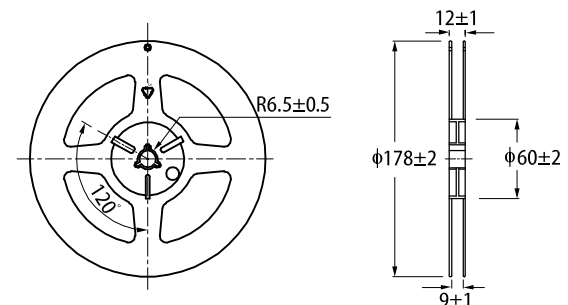
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



TAPE SPECIFICATIONS (units : mm)

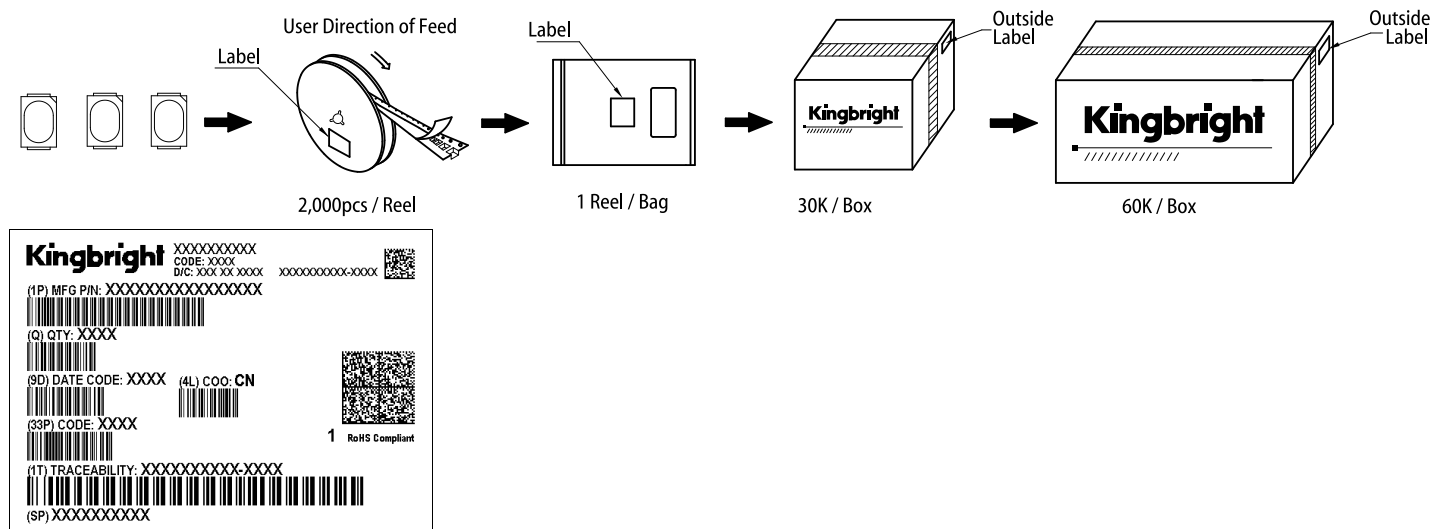


REEL DIMENSION (units : mm)



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

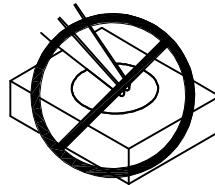
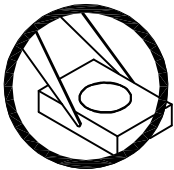
PACKING & LABEL SPECIFICATIONS



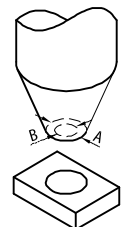
HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.
3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of lead frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.



RELIABILITY TEST ITEMS AND CONDITIONS

The reliability of products shall be satisfied with items listed below

LOT TOLERANCE PERCENT DEFECTIVE (LTPD): 10%

No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test	-	$T_a = 25^{\circ}\text{C}$, $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100(101)	$T_a = 100^{\circ}\text{C}$, $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
3	Low Temp. operating test	-	$T_a = -40^{\circ}\text{C}$, $I_F = \text{maximum rated current}^*$	1,000 h	0 / 22
4	High temp. storage test	EIAJ ED-4701/100(201)	$T_a = \text{maximum rated storage temperature}$	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100(202)	$T_a = -40^{\circ}\text{C}$	1,000 h	0 / 22
6	High temp. & humidity storage test	-	$T_a = 60^{\circ}\text{C}$, RH = 90%	500 h	0 / 22
7	High temp. & humidity operating test	-	$T_a = 60^{\circ}\text{C}$, RH = 90% $I_F = \text{maximum rated current}^*$	500 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100(301)	Moisture soak: 30°C , 70% RH, 72h Preheat: $150\sim 180^{\circ}\text{C}$ (120s max.) Soldering temp: 260°C (10s)	2 times	0 / 18
9	Thermal shock operating test	-	$T_a = -40^{\circ}\text{C}$ (15min) ~ 100°C (15min) $I_F = \text{derated current at } 100^{\circ}\text{C}$	1,000 cycles	0 / 22
10	Thermal shock test	-	$T_a = -40^{\circ}\text{C}$ (15min) ~ maximum rated Storage temperature(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100(304)	$C = 100\text{pF}$, $R_2 = 1.5\text{K}\Omega$ $V = 450\text{V}$	Once each Polarity	0 / 22
12	Vibration test	-	$a = 196\text{m/s}^2$, $f = 100\sim 2\text{KHz}$, $t = 48\text{min}$ for all xyz axes	4 times	0 / 22

* : Refer to forward current vs. derating curve diagram

CRITERIA FOR JUDGING DAMAGE

Items	Symbols	Conditions	Failure Criteria
luminous Intensity	I_V	$I_F = 20\text{mA}$	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V_F	$I_F = 20\text{mA}$	Testing Max. Value $\geq$ Spec. Max. Value x 1.2
Reverse Current	I_R	$V_R = \text{Maximum Rated Reverse Voltage}$	Testing Max. Value $\geq$ Spec. Max. Value x 2.5
High temp. storage test	-	-	Occurrence of notable decoloration, deformation and cracking

PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
- The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
- All design applications should refer to Kingbright application notes available at <https://www.KingbrightUSA.com/ApplicationNotes>